

# NSM0402AT-LL Top-Inlet Analog Silicon Microphone Specification

Rev 1.0



#### 1. GENERAL DESCRIPTION

NSM0402AT-LL is a Silicon Microphone with analog output and top inlet for sound input. It is a cost-effective alternative to traditional electret condenser microphone (ECM). Provided on tap-and-reel, it is ideally suited for high volume applications. And it can be processed directly to customer's PCB using standard automatic pick-and-place equipment and surface mounted via standard solder reflow equipment.

NSM0402AT-LL is a new Silicon Microphone with Maximum RF protection. It uses a new anti-interference circuit to avoid RF interference. It is great convenience for customers to solve terminal RF interference.

NSM0402AT-LL can be used in (but not limited to) the following applications:

- 1. Portable communication device
- 2. Notebook and desktop
- 3. Headphone and headset accessories

#### 2. ABSOLUTE MAXIMUM RATINGS

Supply voltage: VDD to GND	0.3V~5V
ESD Tolerance	
The Lid Mode	8kV
The I/O Pin Mode	4kV

TEMPERATURE CHARACTERISTICS					
Parameter	Conditions	Min	Тур	Max	Unit
Operating Temperature		-40		+85	°C
Store on Tommersture	Solder on PC board	-40		+105	°C
Storage Temperature	In Tape and Reel	-10		+50	°C

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# 3. ACOUSTIC & ELECTRICAL SPECIFICATIONS

Unless otherwise specified, test conditions are:

Typical specifications are measured at VDD =3V

Input sound pressure  $P_{IN} = 94dBSPL@1kHZ$ 

Test room temperature Ta = 25 °C, Room Humidity =  $50 \pm 20\%$ 

SNR & noise floor measurement is based on 20 - 20 KHz pass band with A-Weighting

Filter applied

PERFORMANCE					
Parameter	Conditions	Min Typ Max		Unit	
Directivity			Omni-I	Direction	al
Sensitivity	$(0.1 \text{ VI}_{\text{c}})$		-42		dDry
Sensitivity Tolerance	@1KHz (0 dB = 1V/Pa)	-1	0	1	dBv
Signal-to-Noise Ratio	@1KHz (0 dB = 1V/Pa)		59		dB
Total Harmonic Distortion (THD) @ 94dB SPL	@1KHz			0.5	%
Max Input Sound Pressure	@1KHz, THD < 10%		125		dBSPL
Power Supply Rejection (PSR)	217Hz,100mVpp square wave		-84		dB
	INPUT CHARACTERISTICS				
Power supply Voltage		1.6		3.6	V
Sensitivity Loss Across Power Supply Voltage	Change in sensitivity from 1.6V to 3.6V power supply voltage	No change of		dB	
Total Operation Current	1.6V-3.6V power supply voltage	78		uA	
	OUTPUT CHARACTERISTICS				
Output Impedance	@1KHz (0 dB = 1 V/Pa)			200	Ω

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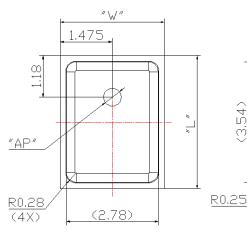
# 4. FREQUENCY RESPONSE CURVE

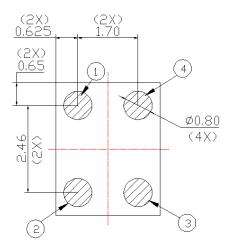


Figure 1. Typical free field frequency response (Normalized to 1 KHz)

″H″

#### 5. MECHANICAL SPECIFICATIONS





ITEM	DIMENSION	TOLERANCE	UNITS
LENGTH(L)	3.76	$\pm 0.10$	mm
WIDTH(W)	2.95	$\pm 0.10$	mm
HEIGHT(H)	1.10	$\pm 0.10$	mm
ACOUSTIC PORT(AP)	φ 0.50	±0.10	mm

PIN OUTPUT		
PIN#	FUNCTION	
1	POWER(Vdd)	
2	GROUND	
3	GROUND	
4	OUTPUT	

Note:

Dimensions are in millimetres unless otherwise specified. Tolerance  $\pm 0.15$ mm unless otherwise specified

Figure 2. Detailed mechanical drawings

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# 6. RECOMMENDED CUSTOMER LANDING PATTERN

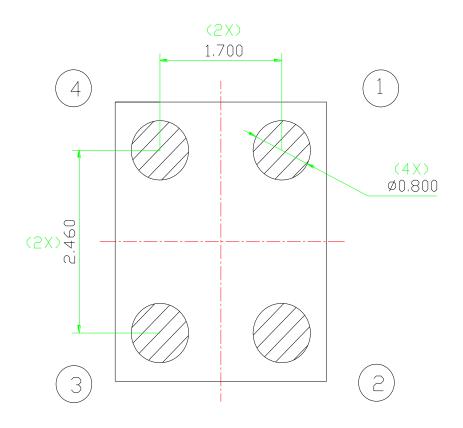


Figure 3. Recommended landing pattern on customers' PCB

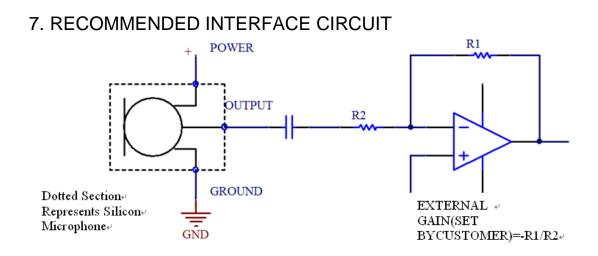
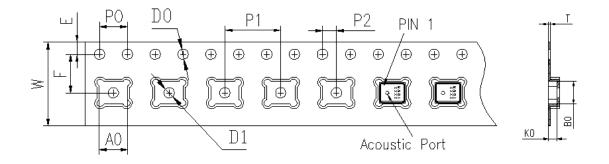


Figure 4. Recommended interface circuit for customers' applications

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# 8. PACKAGING SPECIFICATIONS



D0	1.5±0.10	W	12.0±0.30
D1	$1.5 \pm 0.10$	Е	1.75±0.10
A0	4.06±0.10	F	5.50±0.10
B0	3.30±0.10	P0	4.00±0.10
K0	$1.35 \pm 0.10$	P1	$8.00 \pm 0.10$
Т	0.3±0.05	P2	2.00±0.10

Notes:

(1) Tape & Reel Per EIA-481 standard;

(2) Label applied to external package and direct to reel

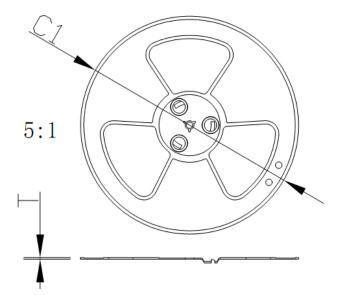
Order Part Number	Reel Diameter	Qty per Reel
NSM0402AT-LL	13"	5,000

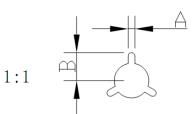
Figure 5. Tape Specification

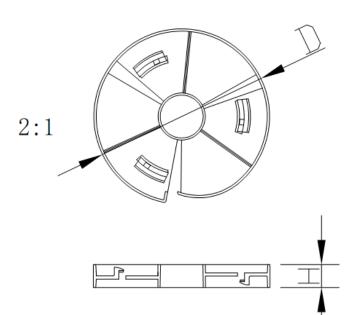
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SPEC	13"
C1±1.0	Ф330
A±0.2	2.6
$B\pm0.2$	10.8
T±0.2	2.0

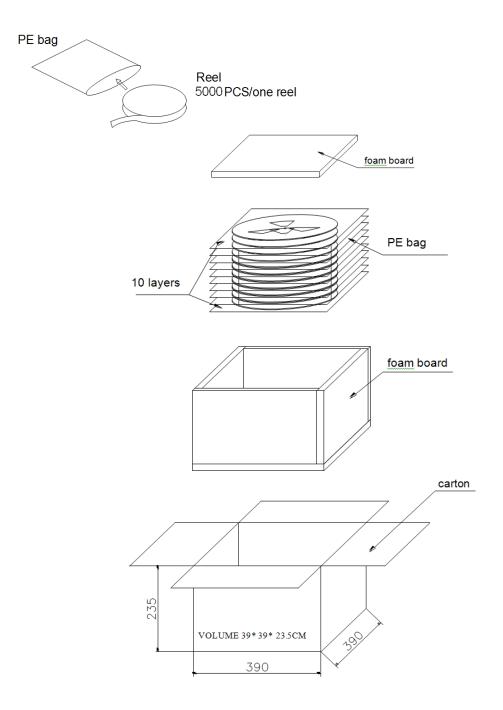
Avaliable Reel Size(mm)			
Tape Width $D \pm 0.5$ H+1			
12	Φ100	12.5	

#### 5,000PCS PRODUCTS/1 reel

Figure 6. Reel Specification

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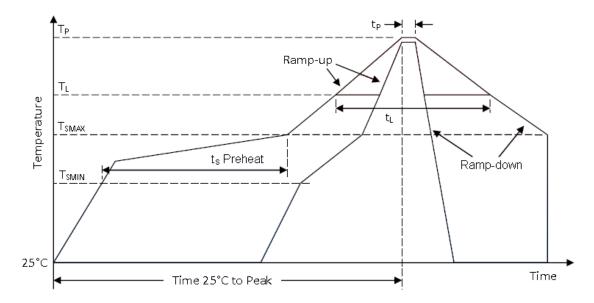
50,000 Pieces of Products per Carton

Figure 7 Packaging Specification

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#### 9. SOLDER REFLOW PROFILE



Profile Feature	Pb-Free
Average Ramp-up rate $(T_{SMAX} \text{ to } T_P)$	3°C/second max.
$\begin{array}{c} \text{Preheat} \\ \text{Temperature Min } (T_{\text{SMIN}}) \\ \text{Temperature Max } (T_{\text{SMAX}}) \\ \text{Time } (T_{\text{SMIN}} \text{ to } T_{\text{SMAX}}) (t_{\text{S}}) \end{array}$	150℃ 200℃ 60-180 seconds
Time maintained above: Temperature (T <sub>L</sub> ) Time (t <sub>L</sub> )	217℃ 60-150 seconds
Peak Temperature (T <sub>P</sub> )	260°C
Time within 5 $^{\circ}$ C of actual Peak Temperature (t <sub>P</sub> )	20-40 seconds
Ramp-down rate( $T_P$ to $T_{SMAX}$ )	6°C/second max
Time 25°C to Peak Temperature	8 minutes max

Figure 8 Recommended leadless solder reflow temperature profile

Notes:

- 1. Vacuuming over acoustical hole of the microphone is not allowed, because the Devices can be damaged by vacuum.
- 2. Washing the board after reflow process is not allowed, because board washing and Cleaning agents can damage the device. A device should not be exposed to ultrasonic processing or cleaning.
- 3. Recommended number of reflow is no more than 5 times.

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#### **10. RELIABILITY SPECIFICATIONS**

Test item	Detail	Standard
Reflow Simulation	Refer to Sec.9 for solder reflow profile, total 5 times	/
Low Temperature Bias	Conditions:-40°C Duration:168 hours while under bias	IEC 60068-2-2 Test Aa
High Temperature Bias	Conditions: 105°C Duration:168 hours while under bias	IEC 60068-2-2 Test Ba
Thermal Shock	Conditions: 100 cycles of air-air thermal shock from -40 °C to 125 °C with 15-minute soaks	IEC 60068-2-4
Temperature/Humidity Bias	Conditions: 85 °C /85%RH environment while under bias for 168 hours	JESD 22-A101A-B
Mechanical Shock	Conditions:3 pulses of 10,000g in the X,Y and Z direction	IEC 60068-2-27 Test Ea
Vibration Test	Test axis: X,Y,Z Conditions: 2~400Hz 1 oct/min Test time: 15 mins per axis Use fixture during the testing	IEC 60068-2-6
Drop Test	Conditions: For each sample, drop by all corners, edges, surfaces respectively. Steel floor. Drop height: 1800mm.	IEC 60068-2-32
ESD	Conditions: $\pm$ 8KV direct contact to the lid when unit is grounded , $\pm$ 4KV direct contact to the I/O pins.10 times	IEC 61000-4-2

Note: Immediately after reliability test, the samples shall be stored under climatic conditions such as that normally exist in ordinary rooms or laboratories. Unless otherwise noted, the recovery period shall be 2 hours at least before performance testing. After test condition is performed, the sensitivity of the microphone shall not deviate more than 3dB from its initial value.

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### 11. REVISION HISTORY:

Version	Date	Description
1.0	12/12/2013	Initial release

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